

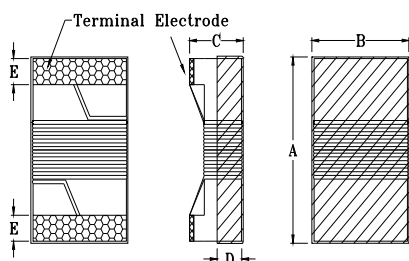
High Frequency Winding Type Chip Inductor SWI1008UO-SERIES

1. Features

1. Ceramic core wire wound construction.
2. No batch to batch variations in inductance.
3. High Reliability due to ceramic wire wound construction.
4. High frequency application.
5. Small footprint as well as low profile.
6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
7. Operating temperature-40~+125°C (Including self - temperature rise).



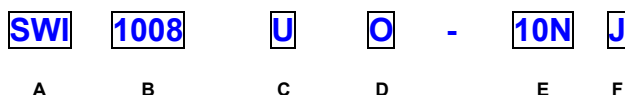
2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SWI1008	2.92 max.	2.79 max.	2.20 max.	1.20 ref.	0.55±0.10

Unit: mm

3. Part Numbering



A: Series
 B: Dimension
 C: Material
 D: Category Code
 E: Inductance
 F: Inductance Tolerance

LxW
 Industrial Grade
 10N=10nH
 G=±2%, J=±5%, K=±10%

4. Specification

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI1008UO-10N□	10	G, J, K	0.1V/50M	50/500	1000	0.08	4100
SWI1008UO-12N□	12	G, J, K	0.1V/50M	50/500	1000	0.09	3300
SWI1008UO-15N□	15	G, J, K	0.1V/50M	50/500	1000	0.18	2500
SWI1008UO-18N□	18	G, J, K	0.1V/50M	50/350	1000	0.11	2500
SWI1008UO-22N□	22	G, J, K	0.1V/50M	55/350	1000	0.12	2400
SWI1008UO-27N□	27	G, J, K	0.1V/50M	55/350	1000	0.13	1600
SWI1008UO-33N□	33	G, J, K	0.1V/50M	60/350	1000	0.14	1600
SWI1008UO-39N□	39	G, J, K	0.1V/50M	60/350	1000	0.15	1500
SWI1008UO-47N□	47	G, J, K	0.1V/50M	65/350	1000	0.16	1500
SWI1008UO-56N□	56	G, J, K	0.1V/50M	65/350	1000	0.18	1300
SWI1008UO-68N□	68	G, J, K	0.1V/50M	65/350	1000	0.20	1300
SWI1008UO-82N□	82	G, J, K	0.1V/50M	60/350	1000	0.22	1000

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI1008UO-R10□	100	G, J,K	0.1V/25M	60/350	650	0.56	1000
SWI1008UO-R12□	120	G, J,K	0.1V/25M	60/350	650	0.63	950
SWI1008UO-R15□	150	G, J,K	0.1V/25M	45/100	580	0.70	850
SWI1008UO-R18□	180	G, J,K	0.1V/25M	45/100	620	0.77	750
SWI1008UO-R22□	220	G, J,K	0.1V/25M	45/100	500	0.84	700
SWI1008UO-R27□	270	G, J,K	0.1V/25M	45/100	500	0.91	600
SWI1008UO-R33□	330	G, J,K	0.1V/25M	45/100	450	1.05	570
SWI1008UO-R39□	390	G, J,K	0.1V/25M	45/100	470	1.12	500
SWI1008UO-R47□	470	G, J,K	0.1V/25M	45/100	470	1.19	450
SWI1008UO-R56□	560	G, J,K	0.1V/25M	45/100	400	1.33	415
SWI1008UO-R62□	620	G, J,K	0.1V/25M	45/100	300	1.40	375
SWI1008UO-R68□	680	G, J,K	0.1V/25M	45/100	400	1.47	375
SWI1008UO-R75□	750	G, J,K	0.1V/25M	45/100	360	1.54	360
SWI1008UO-R82□	820	G, J,K	0.1V/25M	45/100	400	1.61	350
SWI1008UO-R91□	910	G, J,K	0.1V/25M	35/50	380	1.68	320
SWI1008UO-1R0□	1000	G, J,K	0.1V/25M	35/50	370	1.75	290
SWI1008UO-1R2□	1200	G, J,K	0.1V/7.9M	35/50	310	2.00	250
SWI1008UO-1R5□	1500	G, J,K	0.1V/7.9M	28/50	330	2.23	200
SWI1008UO-1R8□	1800	G, J,K	0.1V/7.9M	28/50	300	2.60	160
SWI1008UO-2R2□	2200	G, J,K	0.1V/7.9M	28/50	280	2.80	160
SWI1008UO-2R7□	2700	G, J,K	0.1V/7.9M	22/25	290	3.20	140
SWI1008UO-3R3□	3300	G, J,K	0.1V/7.9M	22/25	290	3.40	110
SWI1008UO-3R9□	3900	G, J,K	0.1V/7.9M	20/25	260	3.60	100
SWI1008UO-4R7□	4700	G, J,K	0.1V/7.9M	18/7.9	200	4.00	32
SWI1008UO-5R6□	5600	G, J,K	0.1V/7.9M	18/7.9	200	4.00	25
SWI1008UO-6R8□	6800	G, J,K	0.1V/7.9M	18/7.9	200	4.90	21
SWI1008UO-8R2□	8200	G, J,K	0.1V/7.9M	16 / 7.9	170	6.00	16
SWI1008UO-100□	10000	G, J,K	0.1V/2.52M	15/7.9	170	8.00	14

Note:

- All test data referenced to 25°C ambient.
- DC current at 25°C that causes the specified inductance drop from its value without current.
- Current that causes the specified temperature rise from 25°C ambient.

This information is for reference only and does not represent absolute maximum ratings.

5. Recommended PC Board Pattern

Chip size							Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWI	1008	2.92max	2.79max	2.20max	1.20 ref	0.55±0.10	3.310	1.526	2.540

